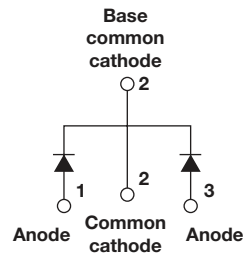


## HEXFRED®

### Ultrafast Soft Recovery Diode, 2 x 8 A


**D<sup>2</sup>PAK**

**FEATURES**

- Ultrafast recovery
- Ultrasoft recovery
- Very low  $I_{RRM}$
- Very low  $Q_{rr}$
- Specified at operating conditions
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- Halogen-free according to IEC 61249-2-21 definition
- Compliant to RoHS directive 2002/95/EC
- AEC-Q101 qualified


**RoHS**  
 COMPLIANT  
 HALOGEN  
**FREE**
**BENEFITS**

- Reduced RFI and EMI
- Reduced power loss in diode and switching transistor
- Higher frequency operation
- Reduced snubbing
- Reduced parts count

**DESCRIPTION**

VS-HFA16TA60CS is a state of the art center tap ultrafast recovery diode. Employing the latest in epitaxial construction and advanced processing techniques it features a superb combination of characteristics which result in performance which is unsurpassed by any rectifier previously available. With basic ratings of 600 V and 8 A per leg continuous current, the VS-HFA16TA60CS is especially well suited for use as the companion diode for IGBTs and MOSFETs. In addition to ultrafast recovery time, the HEXFRED® product line features extremely low values of peak recovery current ( $I_{RRM}$ ) and does not exhibit any tendency to “snap-off” during the  $t_b$  portion of recovery. The HEXFRED features combine to offer designers a rectifier with lower noise and significantly lower switching losses in both the diode and the switching transistor. These HEXFRED advantages can help to significantly reduce snubbing, component count and heatsink sizes. The HEXFRED VS-HFA16TA60CS is ideally suited for applications in power supplies and power conversion systems (such as inverters), motor drives, and many other similar applications where high speed, high efficiency is needed.

PRODUCT SUMMARY	
$V_R$	600 V
$V_F$ at 8 A at 25 °C	1.7 V
$I_{F(AV)}$	2 x 8 A
$t_{rr}$ (typical)	18 ns
$T_J$ (maximum)	150 °C
$Q_{rr}$	65 nC
$di_{(rec)M}/dt$	240 A/ $\mu$ s

ABSOLUTE MAXIMUM RATINGS				
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Cathode to anode voltage	$V_R$		600	V
Maximum continuous forward current	$I_F$	$T_C = 100$ °C	8	A
			per leg	
per device				
Single pulse forward current	$I_{FSM}$		60	
Maximum repetitive forward current	$I_{FRM}$		24	
Maximum power dissipation	$P_D$	$T_C = 25$ °C	36	W
		$T_C = 100$ °C	14	
Operating junction and storage temperature range	$T_J, T_{Stg}$		- 55 to + 150	°C

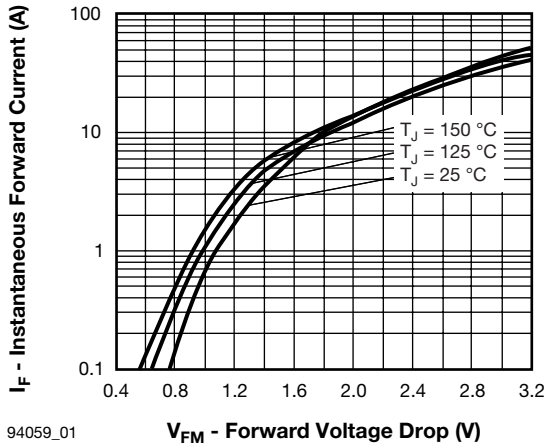
ELECTRICAL SPECIFICATIONS PER LEG ( $T_J = 25\text{ }^\circ\text{C}$ unless otherwise specified)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Cathode to anode breakdown voltage	$V_{BR}$	$I_R = 100\text{ }\mu\text{A}$	600	-	-	V
Maximum forward voltage	$V_{FM}$	$I_F = 8.0\text{ A}$	-	1.4	1.7	
		$I_F = 16\text{ A}$	-	1.7	2.1	
		$I_F = 8.0\text{ A}, T_J = 125\text{ }^\circ\text{C}$	-	1.4	1.7	
Maximum reverse leakage current	$I_{RM}$	$V_R = V_R\text{ rated}$	-	0.3	5.0	$\mu\text{A}$
		$T_J = 125\text{ }^\circ\text{C}, V_R = 0.8 \times V_R\text{ rated}$	-	100	500	
Junction capacitance	$C_T$	$V_R = 200\text{ V}$	-	10	25	pF
Series inductance	$L_S$	Measured lead to lead 5 mm from package body	-	8.0	-	nH

DYNAMIC RECOVERY CHARACTERISTICS PER LEG ( $T_J = 25\text{ }^\circ\text{C}$ unless otherwise specified)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Reverse recovery time See fig. 5, 6 and 16	$t_{rr}$	$I_F = 1.0\text{ A}, dI_F/dt = 200\text{ A}/\mu\text{s}, V_R = 30\text{ V}$	-	18	-	ns
	$t_{rr1}$	$T_J = 25\text{ }^\circ\text{C}$	-	37	55	
	$t_{rr2}$	$T_J = 125\text{ }^\circ\text{C}$	-	55	90	
Peak recovery current See fig. 7 and 8	$I_{RRM1}$	$T_J = 25\text{ }^\circ\text{C}$	-	3.5	5.0	A
	$I_{RRM2}$	$T_J = 125\text{ }^\circ\text{C}$	-	4.5	8.0	
Reverse recovery charge See fig. 9 and 10	$Q_{rr1}$	$T_J = 25\text{ }^\circ\text{C}$	-	65	138	nC
	$Q_{rr2}$	$T_J = 125\text{ }^\circ\text{C}$	-	124	360	
Peak rate of fall of recovery current during $t_b$ See fig. 11 & 12	$dI_{(rec)M}/dt1$	$T_J = 25\text{ }^\circ\text{C}$	-	240	-	$\text{A}/\mu\text{s}$
	$dI_{(rec)M}/dt2$	$T_J = 125\text{ }^\circ\text{C}$	-	210	-	

THERMAL - MECHANICAL SPECIFICATIONS						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Lead temperature	$T_{lead}$	0.063" from case (1.6 mm) for 10 s	-	-	300	$^\circ\text{C}$
Junction to case, single leg conducting	$R_{thJC}$		-	-	3.5	K/W
Junction to case, both legs conducting			-	-	1.75	
Thermal resistance, junction to ambient	$R_{thJA}$	Typical socket mount	-	-	80	
Weight			-	2	-	g
			-	0.07	-	oz.
Mounting torque			6.0 (5.0)	-	12 (10)	kgf · cm (lbf · in)
Marking device		Case style D <sup>2</sup> PAK	HFA16TA60CS			

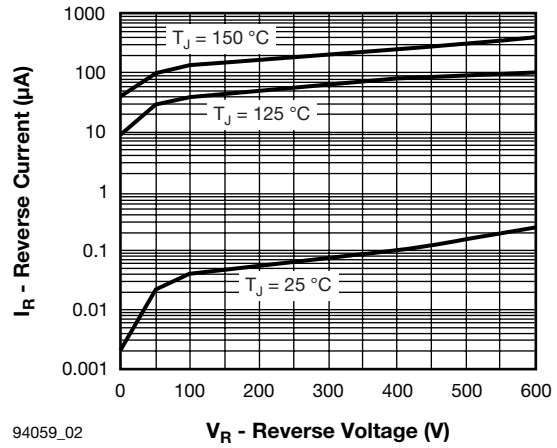
## HEXFRED® Ultrafast Soft Recovery Diode, 2 x 8 A

Vishay High Power Products



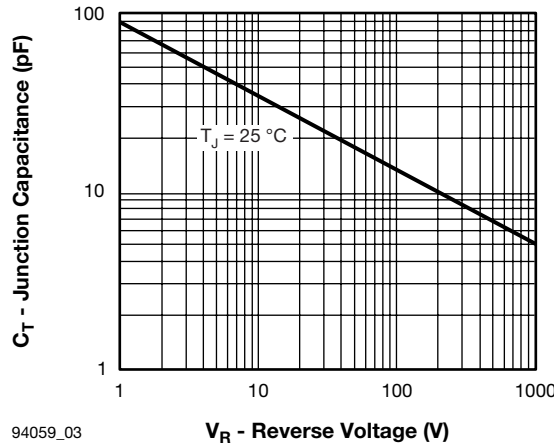
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Fig. 1 - Maximum Forward Voltage Drop vs. Instantaneous Forward Current (Per Leg)



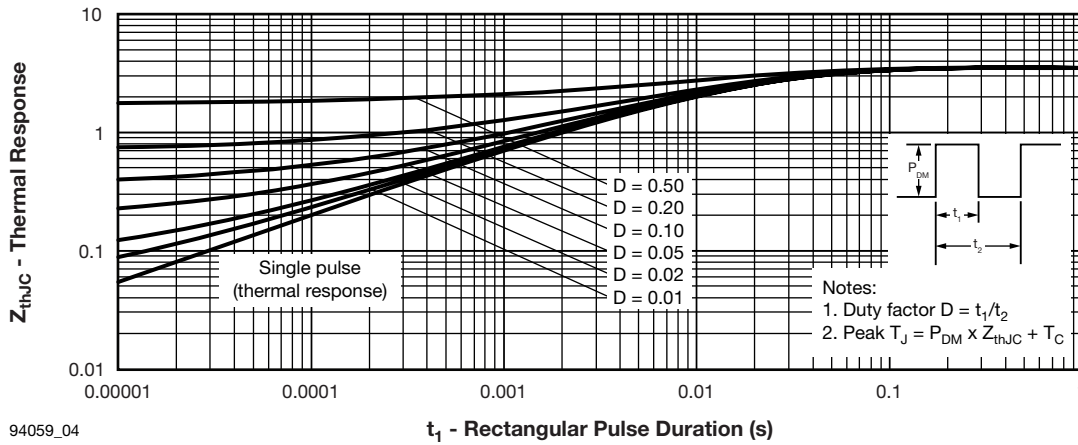
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Fig. 2 - Typical Reverse Current vs. Reverse Voltage (Per Leg)



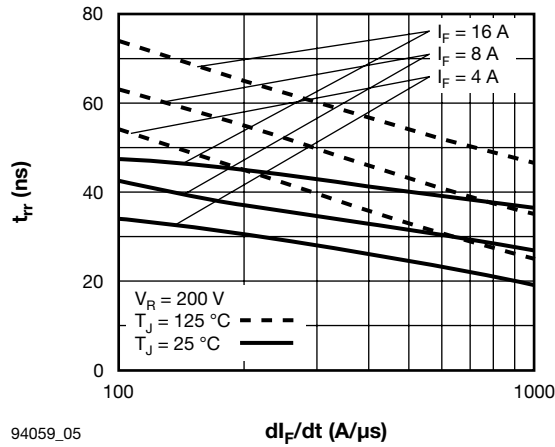
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Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage (Per Leg)



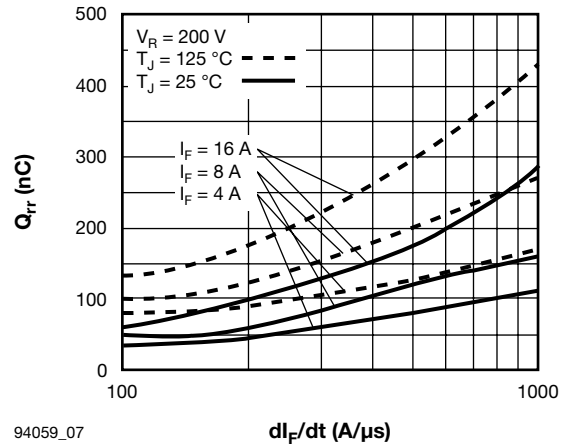
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Fig. 4 - Maximum Thermal Impedance  $Z_{thJC}$  Characteristics (Per Leg)



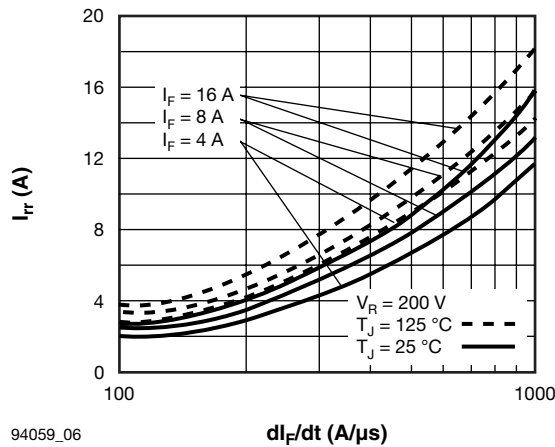
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Fig. 5 - Typical Reverse Recovery Time vs.  $dI_F/dt$  (Per Leg)



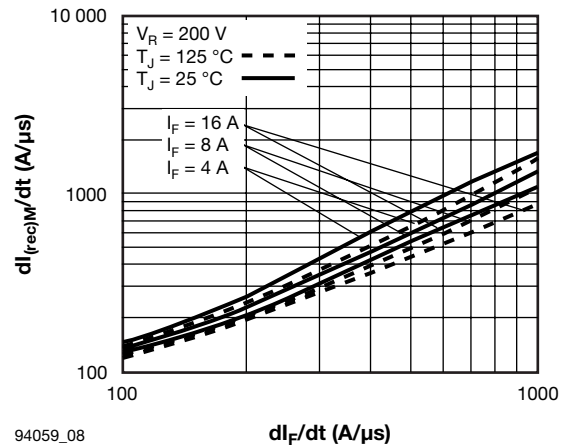
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Fig. 7 - Typical Stored Charge vs.  $dI_F/dt$  (Per Leg)



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Fig. 6 - Typical Recovery Current vs.  $dI_F/dt$  (Per Leg)



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Fig. 8 - Typical  $dI_{recM}/dt$  vs.  $dI_F/dt$  (Per Leg)

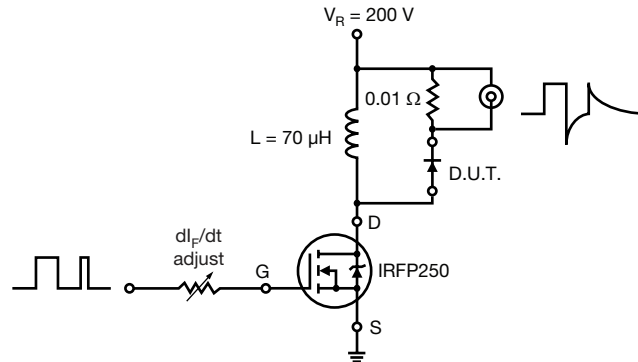
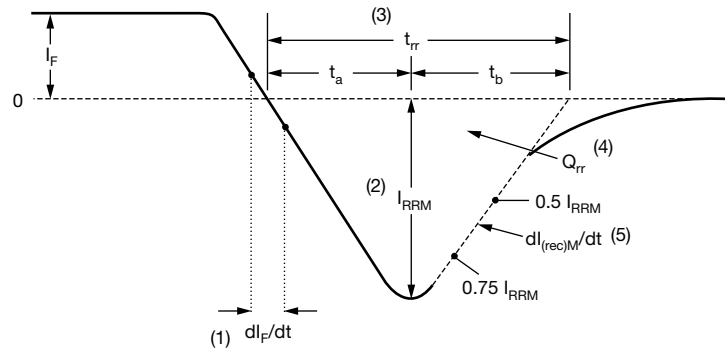


Fig. 9 - Reverse Recovery Parameter Test Circuit



- (1)  $di_F/dt$  - rate of change of current through zero crossing
- (2)  $I_{RRM}$  - peak reverse recovery current
- (3)  $t_{rr}$  - reverse recovery time measured from zero crossing point of negative going  $I_F$  to point where a line passing through  $0.75 I_{RRM}$  and  $0.50 I_{RRM}$  extrapolated to zero current.
- (4)  $Q_{rr}$  - area under curve defined by  $t_{rr}$  and  $I_{RRM}$
- (5)  $dl_{(rec)M}/dt$  - peak rate of change of current during  $t_b$  portion of  $t_{rr}$

$$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$

Fig. 10 - Reverse Recovery Waveform and Definitions

# VS-HFA16TA60CSPbF



Vishay High Power Products

HEXFRED®  
Ultrafast Soft Recovery Diode, 2 x 8 A

## ORDERING INFORMATION TABLE

Device code	VS-	HF	A	16	TA	60	C	S	TRL	PbF
	1	2	3	4	5	6	7	8	9	10

- 1** - HPP product suffix
- 2** - HEXFRED® family
- 3** - Process designator: A = Electron irradiated
- 4** - Current rating (16 = 16 A)
- 5** - Package outline (TA = TO-220, 3 leads)
- 6** - Voltage rating (60 = 600 V)
- 7** - Circuit configuration (C = Common cathode)
- 8** - S = D<sup>2</sup>PAK
- 9** -
  - None = Tube (50 pieces)
  - TRL = Tape and reel (left oriented)
  - TRR = Tape and reel (right oriented)
- 10** - PbF = Lead (Pb)-free

LINKS TO RELATED DOCUMENTS	
Dimensions	<a href="http://www.vishay.com/doc?95046">www.vishay.com/doc?95046</a>
Part marking information	<a href="http://www.vishay.com/doc?95054">www.vishay.com/doc?95054</a>
Packaging information	<a href="http://www.vishay.com/doc?95032">www.vishay.com/doc?95032</a>



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